

PATENT

I hereby certify that on the date specified below, this correspondence is being deposited with the United States Postal Service as first-class mail in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

March 3, 2004

Date



Ayesha J. Shaikh

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : 10/691,020

Confirmation No. : 4992

Applicants : Philip Neaves and Andrew Lever

Filed : October 21, 2003

Attorney Docket No.: 501317.02 (30302/US)

Art Unit : 2829

Customer No. : 27,076

Examiner : Not Yet Assigned

Title : SYSTEM AND METHOD FOR TESTING DEVICES UTILIZING CAPACITIVELY COUPLED SIGNALING

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97 through 1.98, applicants wish to make known to the Patent and Trademark Office the references set forth on the attached form PTO-1449. Copies of the cited foreign patent and non-patent literature references, as required under 37 C.F.R. § 1.98(a)(2), are enclosed. Copies of the cited U.S. patents and U.S. patent application publications will not be submitted herewith in accordance with the waiver by the Office of the requirement under 37 C.F.R. § 1.98(a)(2)(i) for U.S. national patent applications filed after June 30, 2003. Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicants' duty to disclose all information they are aware of which is believed relevant to the examination of the above-identified application, applicants believe that their invention is patentable.

MAR 05 2004

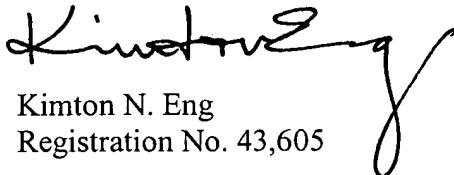
Applicants also wish to make known to the Patent and Trademark Office that an application, Serial No. 10/666,393, describing and claiming subject matter that is similar to the subject matter of this application, was filed on September 17, 2003, which claims priority to United Kingdom Patent Application No. 0311604.3, filed May 20, 2003. This related application, as well as any prior art cited therein, may be material to the examination of this application. A copy of this related application as filed is submitted herewith in accordance with 37 C.F.R. § 1.98(d).

Applicants also wish to make known to the Patent and Trademark Office that an application, Serial No. 10/779,305, describing and claiming subject matter that is similar to the subject matter of this application, was filed on February 13, 2004, which claims priority to United Kingdom Patent Application No. 0323992.8, filed October 13, 2003. This related application, as well as any prior art cited therein, may be material to the examination of this application. A copy of this related application as filed is submitted herewith in accordance with 37 C.F.R. § 1.98(d).

Please acknowledge receipt of this Supplemental Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

Respectfully submitted,

DORSEY & WHITNEY LLP



Kimton N. Eng
Registration No. 43,605

KNE:ajs

Enclosures:

Postcard
Form PTO-1449
Cited References (13)
Copies of Related Applications (2)

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FORM PTO-1449 (REV.7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 501317.02 (30302/US)	APPLICATION NO. 10/691,020
O I P E INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)		APPLICANT(S) Philip Neaves and Andrew Lever	
MAR 05 2004		FILING DATE October 21, 2003	GROUP ART UNIT 2829

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
AA	5,673,130	09/30/97	Sundstrom et al.	359	158	
AB	6,188,232 B1	02/13/01	Akram et al.	324	755	
AC	6,310,494 B1	10/30/01	Ehben et al.	326	82	
AD	6,357,025 B1	03/12/02	Tuttle	714	724	
AE	6,368,930 B1	04/09/02	Enquist	438	320	
AF	6,396,292 B2	05/28/02	Hembree et al.	324	755	
AG	6,407,566 B1	06/18/02	Brunelle et al.	324	758	
AH	6,425,107 B1	07/23/02	Caldara et al.	714	759	
AI	6,490,188 B2	12/03/02	Nuxoll et al.	365	63	
AJ	6,563,133 B1	05/13/03	Tong	257	52	
AK	6,563,299 B1	05/13/03	Van Horn et al.	324	158.1	
AL	6,620,638 B1	09/16/03	Farrar	438	14	
AM	6,625,073 B1	09/23/03	Beffa	365	201	
AN	2001/0054908 A1	12/27/01	Farnworth et al.	324	755	
AO						

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
AP	0 277 764 A3	01/27/88	EP			X	
AQ	0 366 263 A3	05/02/90	EP			X	
AR	0 492 806 A3	11/26/91	EP			X	
AS	0 805 356 A3	04/22/98	EP			X	
AT	2 353 401 A	02/21/01	GB			X	
AU	2 353 402 A	02/21/01	GB			X	
AV	WO 0215185 A1	02/21/02	PCT			X	

EXAMINER

DATE CONSIDERED

* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).

FORM PTO-1449 (REV.7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 501317.02 (30302/US)	APPLICATION NO. 10/691,020
INFORMATION DISCLOSURE STATEMENT <i>(Use several sheets if necessary)</i>		APPLICANT(S) Philip Neaves and Andrew Lever		
		FILING DATE October 21, 2003	GROUP ART UNIT 2829	

OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

AW	"International Technology Roadmap for Semiconductors", Assembly and Packaging, 2001, pp. 1-21.		
AX	Karnezos, M. et al., "System in a Package (SiP) Benefits and Technical Issues", in <i>Proceedings of APEX</i> , San Diego, California, 2002, 7 pages.		
AY	Mick, S. et al., "4Gbps High-Density AC Coupled Interconnection", Department of Electrical and Computer Engineering North Carolina State University, IEEE Custom Integrated Circuits Conference, May 12-16, 2002, pp. 133-140.		
AZ	"Rapidly Advancing System-in-Package Fabrication Technology", Vol. 20, No.3, 2002, pp. 3-11.		
BA	Scanlan, C.M. et al., "System-In-Package Technology, Application and Trends", 2001 Proceedings of SMTA International, Rosemont, Illinois, pp. 764-773.		
BB	Wang, M. et al., "Configurable Area-IO Memory for System-In-A-Package (SiP)", 27 th European Solid-State Circuits Conference, September, 2001, 4 pages.		
BC			
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BI			

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* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).	